WHAT IS CLAIMED IS:

1. A method of manufacturing a circuit wiring board comprising,

preheating a circuit component mounted structure to a preheating temperature, the circuit component mounted structure including a wiring board having first and second electrodes, a first circuit component mounted on the first electrode, a second circuit component mounted on the second electrode via a projecting electrode, and an encapsulating resin composition having a flux function formed in a gap between the second circuit component and the wiring board facing the second circuit component and having a hardening accelerating temperature higher than the preheating temperature and not higher than a heating temperature, and

heating the circuit component mounted structure to the heating temperature from the preheating temperature to perform soldering of the first electrode and the first circuit component and soldering of the second electrode and second circuit component simultaneously with hardening of the encapsulating resin composition having a flux function.

2. A method according to claim 1, wherein the structure is preheated at the temperature of not less than 120℃ and less than 220℃.

3. A method according to claim 1, wherein the

structure is heated at the temperature of 210℃ to 240℃.

4. A method according to claim 1, wherein the hardening accelerating temperature is not less than 190℃ to less than 230℃.

5. A circuit wiring board comprising a wiring board having first and second electrodes, a first circuit component mounted on the first electrode, and a second circuit component mounted on the second electrode via a projecting electrode, wherein the circuit wiring board is obtained by a method in which a structure mounted with the first and second circuit components including an encapsulating resin composition which has a flux function and a hardening accelerating temperature higher than a preheating temperature and not higher than a heating temperature and is formed in a gap between the second circuit component and the wiring board facing the second circuit component, is preheated at the preheating temperature, and heated by raising a temperature from the preheating temperature to the heating temperature to perform soldering of the first electrode and the first circuit component and soldering of the second electrode and second circuit component simultaneously with hardening of the encapsulating resin composition having a flux function.

6. A board according to claim 5, wherein the encapsulating resin composition contains an epoxy-based

thermosetting resin, flux component, and hardener.

7. A board according to claim 6, wherein the hardener is one member selected from the group consisting of phenol-based, acid anhydride-based, and amine-based hardeners containing an OH group, and added in amount of 5 to 20 parts by weight, if the hardener is a solid, and in amount of 10 to 50 parts by weight, if the hardener is a liquid, with respect to 100 parts by weight of the encapsulating resin composition.

8. A board according to claim 5, wherein the encapsulating resin has a viscosity of 1 to 30 Pa・S at room temperature.

9. A board according to claim 5, wherein the preheating temperature is not less than 120℃ and less than 220℃.

10. A board according to claim 5, wherein the heating temperature is 210℃ to 240℃.

11. A board according to claim 5, wherein the hardening accelerating temperature is not less than 190℃ less than 230℃.